

## ABSTRACT

The present invention provides a method for manufacturing a semiconductor device, including: a step A of providing a laminate in which an electronic component is mounted onto a body to be Mounted, a step B of providing a laminated sheet having a sealing sheet for sealing an electronic component and a functional layer made of a different material from that of the sealing sheet, a step C of arranging the laminate on a heating plate with a surface on which the electronic component is mounted facing up and arranging the laminated sheet on the surface of the laminate on which the electronic component is mounted with a sealing sheet surface facing down, and a step D of heat-pressing the laminated sheet to embed the electronic component into the sealing sheet and seal the electronic component after the step C; wherein at least a part of the lateral surface of the functional layer is covered with a resin constituting the sealing sheet after the step D.